


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 01 January 2014 [Approved on 06 February 2026, 11:11 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.258%	Silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	75.038%	Carbon black	1333-86-4	0.5%
			Magnesium hydroxide (Mg(OH) ₂)	1309-42-8	2%
			Phenol, polymer with formaldehyde	9003-35-4	8.5%
			Oxirane, (chloromethyl)-, homopolymer	24969-06-0	14%
			Quartz (SiO ₂) Exempt from other regulatory requirements	14808-60-7	75%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.069%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	3.202%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	21.433%	Elemental nickel REACH Article 67 Exemption	7440-02-0	42%
			IRON, ELEMENTAL	7439-89-6	58%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-123F (JS) Pb&H-free	Diode SMD	0.0106	g

